# Product Change Notification: MAAN-15EMQH513

## Date:

23-Feb-2026

## Product Category:

Memory

## Notification Subject:

CCB 7792.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected 25CS320, 25CS640, 24LC0xxx, 24AA0xxx, 24FC0xx, 24FC1xx, 93C76xx, 93C86xx, 93LC76xx, 93AA76xx, 93AA86xx, 25LC08xx, 25LC16xx, 25LC32xx, 25LC64xx, 25AA08xx, 25AA16xx, 25AA32xx and 25AA64xx device families available in 8L MSOP (3x3mm) package at MTAI assembly site.

## Affected CPNs:

**MAAN-15EMQH513_Affected_CPN_02232026.pdf**
**MAAN-15EMQH513_Affected_CPN_02232026.csv**

**PCN Status:** Final Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for selected 25CS320, 25CS640, 24LC0xxx, 24AA0xxx, 24FC0xx, 24FC1xx, 93C76xx, 93C86xx, 93LC76xx, 93AA76xx, 93AA86xx, 25LC08xx, 25LC16xx, 25LC32xx, 25LC64xx, 25AA08xx, 25AA16xx, 25AA32xx and 25AA64xx device families available in 8L MSOP (3x3mm) package at MTAI assembly site.

**Pre and Post Summary Changes**:

| | **Pre Change** | **Post Change** | **Change** (Yes/No) |
|---|---|---|---|
| **Assembly Site** | Microchip Technology | Microchip Technology Thailand (HQ) (MTAI) | No |

<table>
<tr><td></td><td colspan="2">Thailand<br>(HQ)<br>(MTAI)</td><td></td><td></td></tr>
<tr><td><b>Wire Material</b></td><td colspan="2">Au</td><td>CuPdAu</td><td>Yes</td></tr>
<tr><td><b>Die Attach Material</b></td><td colspan="2">8390A</td><td>8390A</td><td>No</td></tr>
<tr><td><b>Molding Compound Material</b></td><td colspan="2">G600V</td><td>G600V</td><td>No</td></tr>
<tr><td><b>Lead-Frame Material</b></td><td colspan="2">CDA194</td><td>CDA194</td><td>No</td></tr>
<tr><td><b>Lead-Frame DAP Surface Prep</b></td><td>Ag</td><td>Bare Cu</td><td>Bare Cu</td><td>Yes</td></tr>
</table>

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new wire material at MTAI assembly site.

**Change Implementation Status:** In Progress

**Estimated First Ship Date:** 13 May 2026 (date code: 2620)

**Note Below EFSD:** Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Timetable Summary**:

| | **February 2026** | | | | > | **May 2026** | | | | |
|---|---|---|---|---|---|---|---|---|---|---|
| **Work Week** | 06 | 07 | 08 | 09 | | 19 | 20 | 21 | 22 | 23 |
| **Qual Report Availability** | | | | x | | | | | | |
| **Final PCN Issue Date** | | | | x | | | | | | |
| **Estimated Implementation Date** | | | | | | | x | | | |

**Method to Identify Change:** Traceability Code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

**Revision History:** February 23, 2026: Issued final notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

## Attachments:

**PCN_MAAN-15EMQH513_Qual Report.pdf**

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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